



ChipLED 0805 Series
2.0*1.25*0.85mm
Single Color Package



A representative image

ChipLED 0805 Purple Series

Description

- These ChipLEDs are designed in an industry-standard package.
- Various LED colors are available in seven compact, single-color packages.
- The YY0805 has the industry-standard 2.0 mm × 1.25 mm footprint, which is excellent for all-around use.
- These ChipLEDs are packaged in tape and reel with 3000 units in general per reel.
- All packages are compatible with IR reflow solder processes.
- The small size and wide viewing angle,

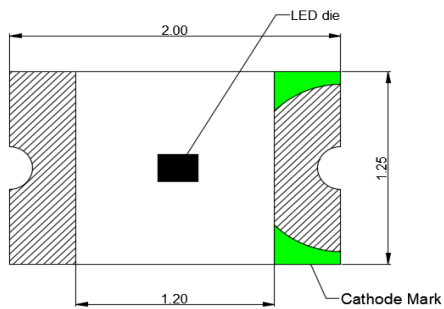
Features and Benefits

- Small size, Industry-standard footprint
- Compatible with Infrared solder process
- Compatible with automatic placement equipment
- Operating temperature range of -40°C to $+85^{\circ}\text{C}$
- Viewing angle: 140°
- Right angle and reverse mount package available
- Various colors available
- Available in 8-mm tape, 7" reel (3000 pcs/reel), Meets EIA STD package
- Moisture sensitivity level: 3
- Halogen-free , RoHS and REACH compliant

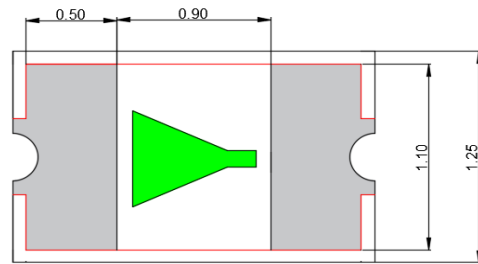
Applications

- Keypad backlighting
- Push-button and switch backlighting
- LCD backlighting
- Symbol backlighting
- Front-panel indicator
- Optical indicator
- Home and smart appliances
- Wearable and portable devices
- Toys
- Displays for industrial control systems

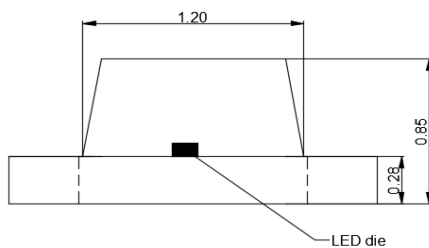
Package Drawing



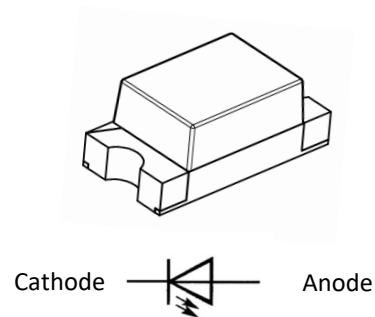
Top View



Bottom View



Side View



Polarity

Note:

1. All dimensions are in millimeters.
2. Tolerance is ± 0.1 mm unless otherwise specified.

Part Table

#	Part Number	Emission Color	Polarity	Zener	Binning Current (mA)	Luminous Intensity (mcd)	Dominant Wavelength (nm)	Forward Voltage (V)	Remark
1	YY0805PU-NN1S0-T3AR4	Purple			5	4-10	390-410	2.8-3.4	
2	YY0805PU-NN3S0-T3AR4	Purple			20	14-34	390-415	2.8-3.4	

Absolute Maximum Ratings for at Ta = 25°C

Parameter	Symbol	Rating	Unit
Reverse Voltage	V_R	5	V
Forward Current	I_F	20	mA
Peak Forward Current(Duty 1/10 @1KHz)	I_{FP}	60	mA
Power Dissipation	P_d	70	mW
Electrostatic Discharge	ESD_{HBM}	> 2000	V
Operating Temperature	T_{opr}	-40 ~ +85	°C
Storage Temperature	T_{stg}	-40 ~ +85	°C
Soldering Temperature	T_{sol}	Reflow Soldering : 260 °C for 10 sec.	
		Hand Soldering : 300 °C for 3 sec.	

Luminous Intensity (Iv) Bin Limits

Bin ID	Luminous Intensity(mcd)	
	Min.	Max.
P03	4	6
P04	6	8
P05	8	10
P09	14	17
P10	17	20
P11	24	24
P12	24	28
P13	28	34

Forward Voltage(V) Bin Limits

Bin ID	Forward Voltage(V)	
	Min.	Max.
VO	2.8	2.9
VP	2.9	3.0
VQ	3.0	3.1
VR	3.1	3.2
VS	3.2	3.3
VT	3.3	3.4

Dominant Wavelength (nm) Bin Limits

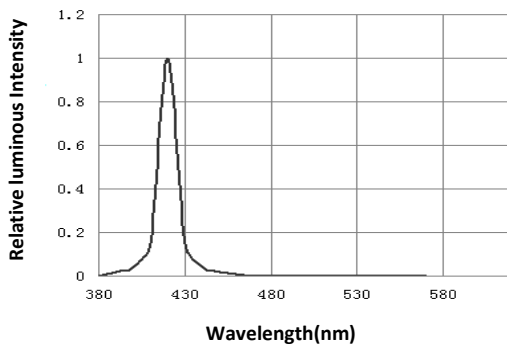
Bin ID	Dominant Wavelength (nm)	
	Min.	Max.
P2	390	395
P3	395	400
P4	400	405
P5	405	410
P6	410	415

- * Tolerance of measurement of luminous intensity is $\pm 10\%$.
- * Tolerance of measurement of forward voltage is $\pm 0.05V$.
- * Tolerance of measurement of dominant wavelength is $\pm 1\text{ nm}$.

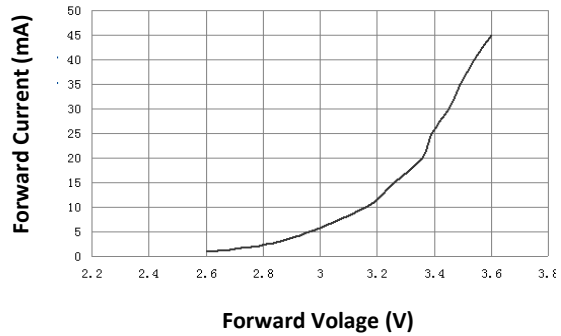
TYPICAL ELECTRO-OPTICAL CHARACTERISTICS CURVES($T_a=25^{\circ}\text{C}$)

The data below are collected from statistical figures that do not necessarily correspond to the actual parameters of each single LED. Hence, these data will be changed without further notice.

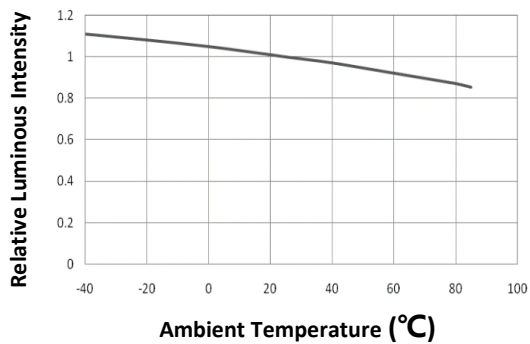
Spectrum Distribution



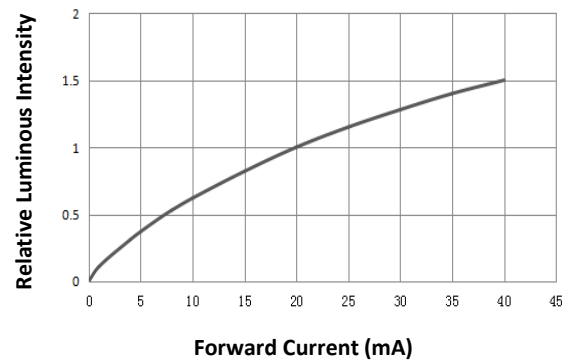
Forward Current vs. Forward Voltage



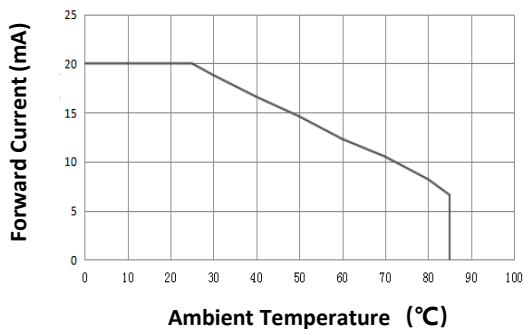
Luminous Intensity vs. Ambient Temperature



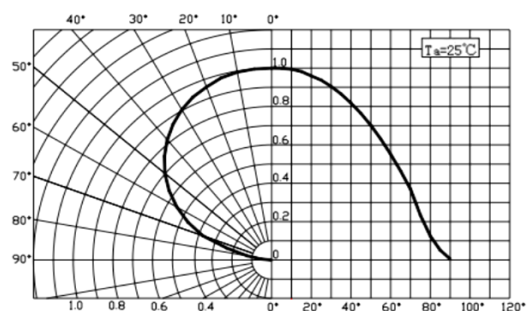
Luminous Intensity vs. Forward Current



Forward Current Derating Curve

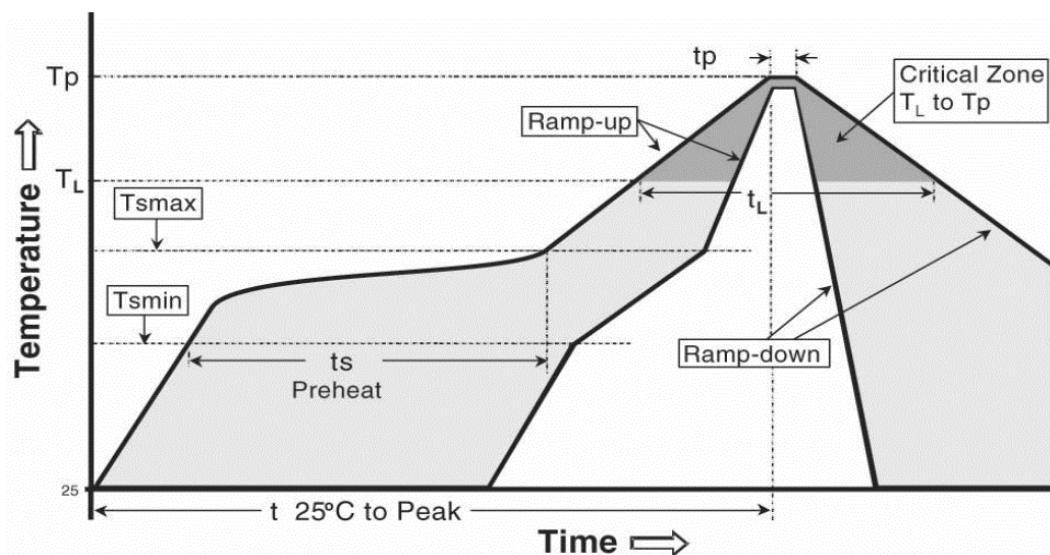


Radiation Diagram



REFLOW SOLDERING

- The ChipLED is rated as a MSL3 as general request product.
- The recommended floor life out of bag is 24hrs.
- The temperature profile is as below.



IPC/JEDEC J-STD-020C

Profile Feature	Pb-Free Assembly
Average ramp-up rate(T_{smax} to T_p)	3°C/second max.
Preheat	
- Temperature Min(T_{smin})	150°C
- Temperature Max(T_{smax})	200°C
- Time(T_{smin} to T_{smax})	60-180 seconds
Time maintained above	
- Temperature(T_L)	217°C
- Time(T_L)	60-150 seconds
Peak Temperature(T_p)	260°C
Time within 5°C of actual peak Temperature(t_p) ²	20-40 seconds
Ramp-down Rate	6°C/second max.
Time 25°C to peak Temperature	8 minutes max.

Moisture Sensitivity

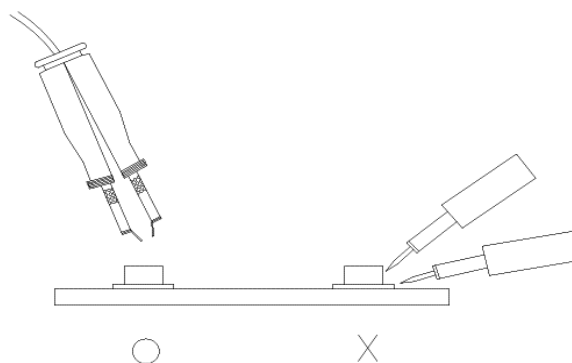
- Yongyu recommends keeping ChipLEDs in the provided, resealable moisture-barrier packaging (MBP) until immediately prior to soldering. Unopened MBPs that contain ChipLEDs do not need special storage for moisture sensitivity.
- Once the MBP is opened, ChipLEDs may be stored as MSL 3 per IPC/JEDEC J-STD-020C, meaning they have one year of floor life in conditions of $\leq 30^{\circ}\text{C}/60\%$ relative humidity (RH). Regardless of the storage condition, Yongyu LED recommends sealing any unsoldered ChipLEDs in the original MBP.

Handling

- The packaging sizes of these SMD products are very small. Users are required to handle with care.
- To avoid damaging the product's surface and interior device, it is recommended to choose a special nozzle to pick up the SMD products during the process of SMT production. If handling is necessary, take special care when picking up these products.

Repairing

Repair should not be recommended after SMT production. When repairing is needed, a double-head soldering iron should be used (as below figure). It should be assured before handling whether the electrical and optical characteristics of the LEDs will or will not be damaged by repairing.



PACKING

- The LEDs are packed in cardboard boxes after packaging in normal or anti-electrostatic bags.
- Cardboard boxes will be used to protect the LEDs from mechanical shock during transportation.
- The boxes are not water resistant, and they must be kept away from water and moisture.
- The reel pack is applied in SMD LED.
- 3000pcs per reel.

